

# BAS85

## Schottky barrier diode

Rev. 6 — 10 September 2010

Product data sheet

## 1. Product profile

### 1.1 General description

Planar Schottky barrier diode with an integrated guard ring for stress protection, encapsulated in a small hermetically sealed glass SOD80C Surface-Mounted Device SMD package with tin-plated metal discs at each end. It is suitable for “automatic placement” and as such it can withstand immersion soldering.

### 1.2 Features and benefits

- Low forward voltage
- High breakdown voltage
- Guard-ring protected
- Hermetically sealed glass SMD package

### 1.3 Applications

- Ultra high-speed switching
- Voltage clamping
- Protection circuits
- Blocking diodes

### 1.4 Quick reference data



Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_F$	forward current		-	-	200	mA
$V_R$	reverse voltage		-	-	30	V
$V_F$	forward voltage	$I_F = 100 \text{ mA}$	-	-	800	mV



## 2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Graphic symbol
1	cathode	[1]	 sym001
2	anode		

[1] The marking band indicates the cathode.

## 3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BAS85	-	hermetically sealed glass surface-mounted package; 2 connectors	SOD80C

## 4. Marking

Table 4. Marking codes

Type number	Marking code
BAS85	marking band

## 5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_R$	reverse voltage		-	30	V
$I_F$	forward current		-	200	mA
$I_{F(AV)}$	average forward current	[1]	-	200	mA
$I_{FRM}$	repetitive peak forward current	$t_p \leq 1$ s; $\delta \leq 0.5$	-	300	mA
$I_{FSM}$	non-repetitive peak forward current	$t_p = 10$ ms	-	5	A
$T_j$	junction temperature		-	125	°C
$T_{amb}$	ambient temperature		-65	+125	°C
$T_{stg}$	storage temperature		-65	+150	°C

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

## 6. Thermal characteristics

**Table 6. Thermal characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	320	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

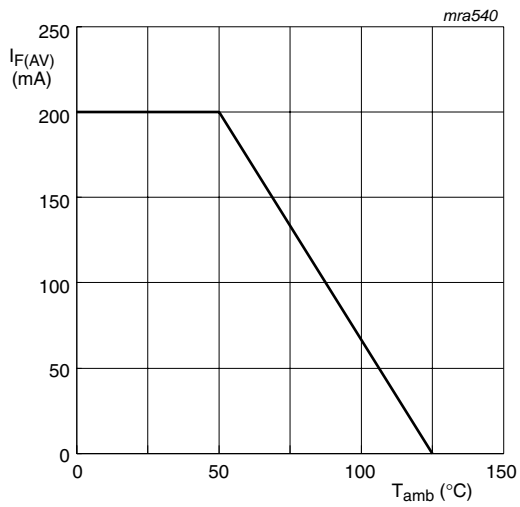
## 7. Characteristics

**Table 7. Characteristics**

$T_{amb} = 25\text{ }^{\circ}\text{C}$  unless otherwise specified.

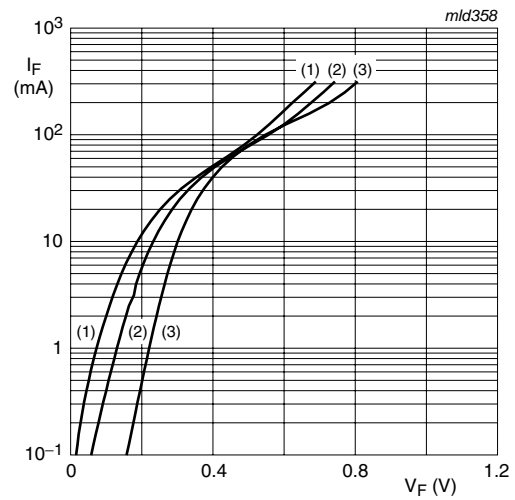
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_F$	forward voltage	$I_F = 0.1\text{ mA}$	-	-	240	mV
		$I_F = 1\text{ mA}$	-	-	320	mV
		$I_F = 10\text{ mA}$	-	-	400	mV
		$I_F = 30\text{ mA}$	-	-	500	mV
		$I_F = 100\text{ mA}$	-	-	800	mV
$I_R$	reverse current	$V_R = 25\text{ V}$	[1]	-	2.3	$\mu\text{A}$
$C_d$	diode capacitance	$V_R = 1\text{ V}; f = 1\text{ MHz}$	-	-	10	pF

[1] Pulse test:  $t_p \leq 300\text{ }\mu\text{s}$ ;  $\delta \leq 0.02$ .



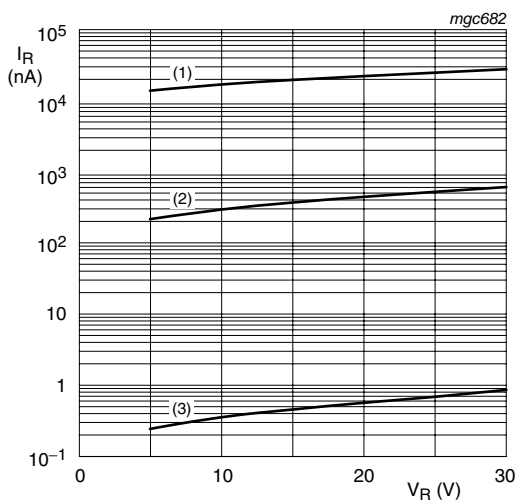
FR4 PCB, standard footprint

**Fig 1. Average forward current as a function of ambient temperature; derating curve**



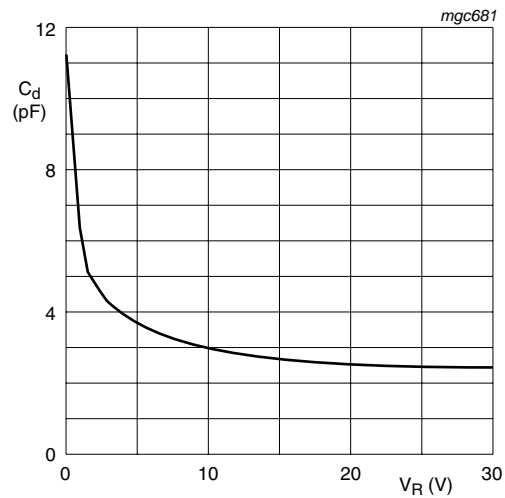
- (1) T<sub>amb</sub> = 125 °C
- (2) T<sub>amb</sub> = 85 °C
- (3) T<sub>amb</sub> = 25 °C

**Fig 2. Forward current as a function of forward voltage; typical values**



- (1) T<sub>amb</sub> = 85 °C
- (2) T<sub>amb</sub> = 25 °C
- (3) T<sub>amb</sub> = -40 °C

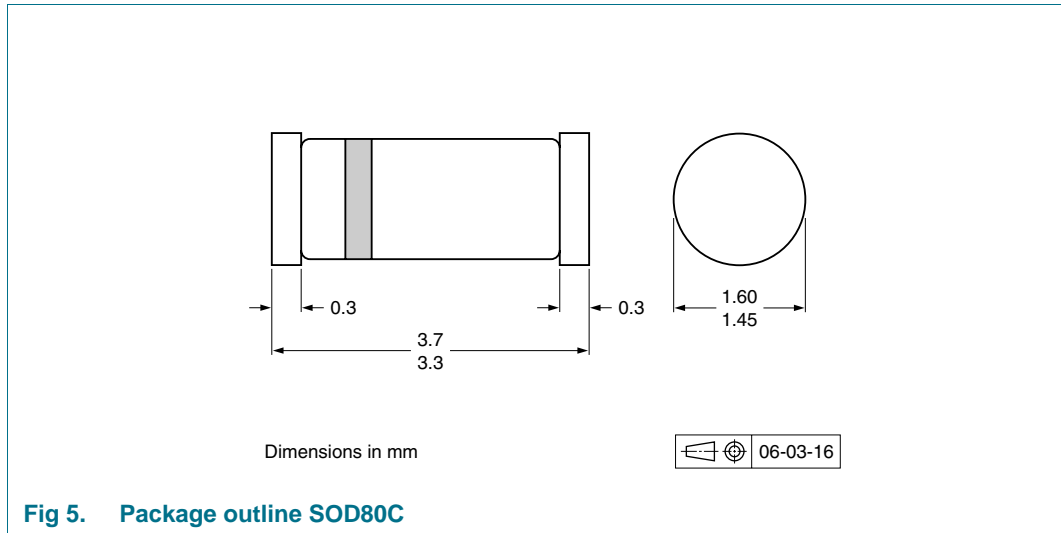
**Fig 3. Reverse current as a function of reverse voltage; typical values**



f = 1 MHz; T<sub>amb</sub> = 25 °C

**Fig 4. Diode capacitance as a function of reverse voltage; typical values**

## 8. Package outline



## 9. Packing information

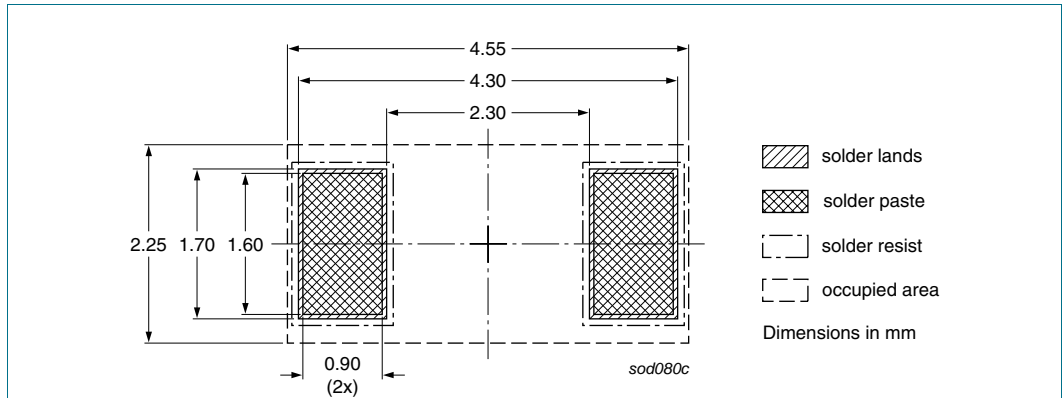
**Table 8. Packing methods**

The indicated -xxx are the last three digits of the 12NC ordering code.<sup>[1]</sup>

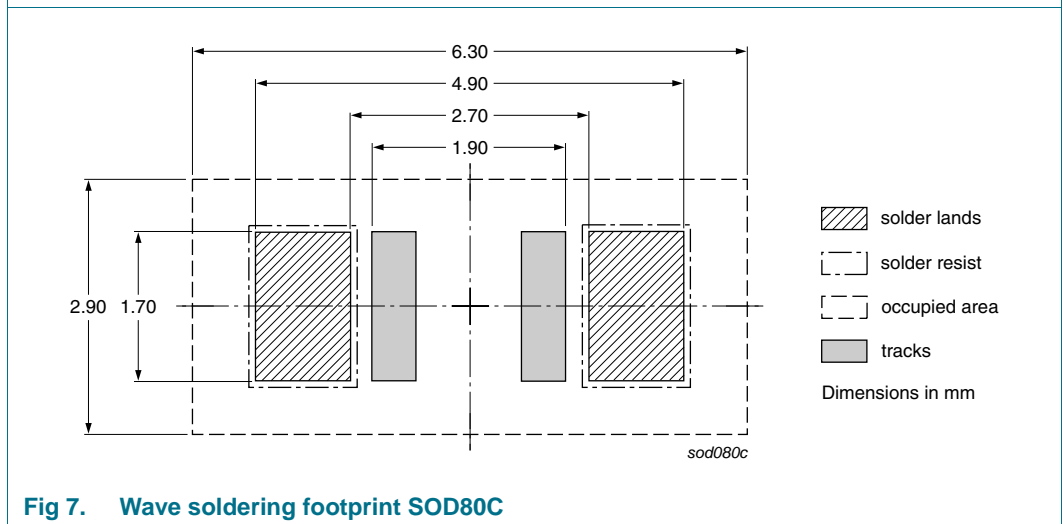
Type number	Package	Description	Packing quantity	
			2500	10000
BAS85	SOD80C	4 mm pitch, 8 mm tape and reel	-115	-135

[1] For further information and the availability of packing methods, see [Section 13](#).

## 10. Soldering



**Fig 6. Reflow soldering footprint SOD80C**



**Fig 7. Wave soldering footprint SOD80C**

## 11. Revision history

Table 9. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BAS85_6	20100910	Product data sheet	-	BAS85_5
Modifications:		<ul style="list-style-type: none"><li>• <a href="#">Section 4 "Marking"</a>: updated</li><li>• <a href="#">Section 12 "Legal information"</a>: updated</li></ul>		
BAS85_5	20090325	Product data sheet	-	BAS85_4
BAS85_4	20000525	Product specification	-	BAS85_3
BAS85_3	19961001	Product specification	-	BAS85_2
BAS85_2	19960320	Product specification	-	-

## 12. Legal information

### 12.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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